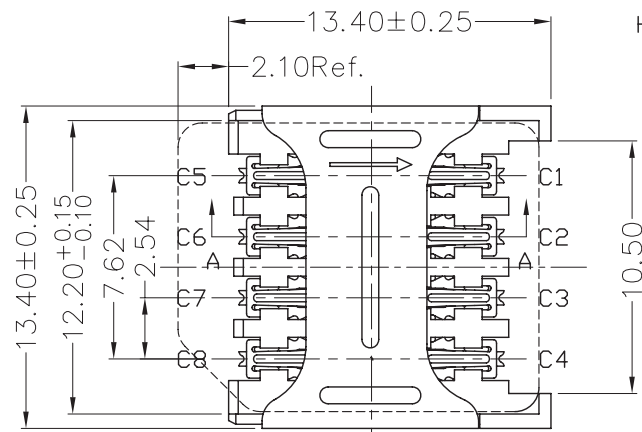
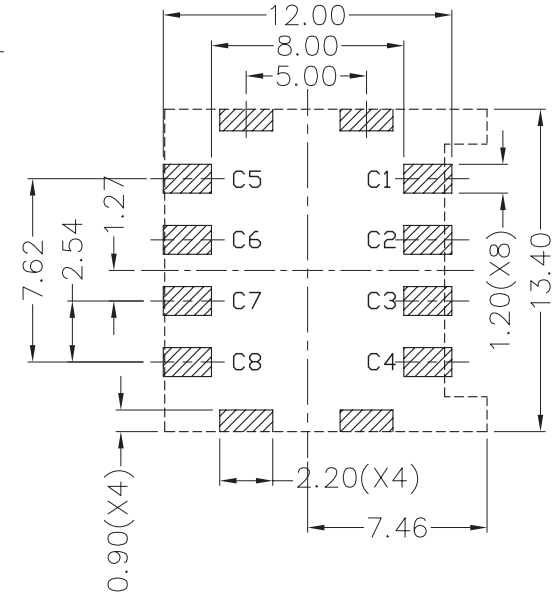
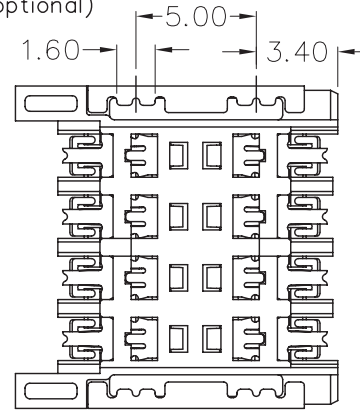
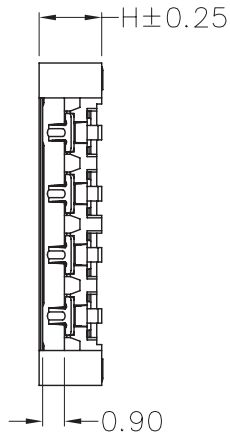


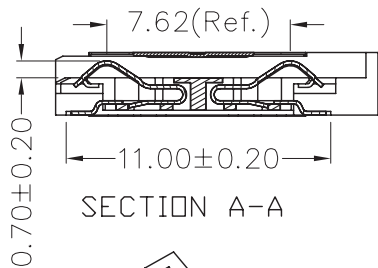
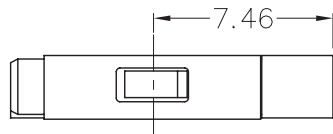
REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



H=2.40/2.60/2.80 mm(optional)



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)



TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 13.40LX13.40WX2.40/2.60/2.80H mm

Weight: Approx0.50±0.1g

Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical,100mΩ max

Insulation resistance:>1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C,30sec.Max

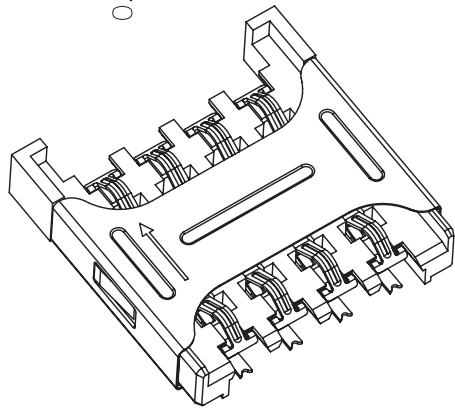
IR reflow: 250°C,5sec.Max

Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C

Operating humidity: 10%~+95%RH



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6/8	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless steel	SMT area:Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X'	±5'
X.X	±0.25	X.X'	±4'
X.XX	±0.15	X.XX'	±3'
X.XXX	±0.10	X.XXX'	±2'

PROJ. UNIT MM SCALE 1:1

Wellco T&C Co., Ltd.

NAME: **Micro-SIM Card Connector**

MODEL NO: **790**

TYPE: **8Pin (Optional)**

DRAWN	Zoey Mar.04.2011	DWG NO.:	790-007
CHECKED	Sean Mar.04.2011	SHEET	1/1
APPROVAL	Simon Mar.04.2011	REVISION	X1



CUSTOMER DRAWING